

# Multilayer Ceramic Chip Capacitors

## CGA9P2X7R1H685K250KA



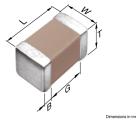






#### TDK item description CGA9P2X7R1H685KT\*\*\*\*

Applications	Automotive Grade
Feature	General General (Up to 50V)  AEC-Q200 AEC-Q200
Series	CGA9(5750) [EIA 2220]
Status	Production (Not Recommended for New Design)



	Size	
Length(L)	5.70mm ±0.40mm	
Width(W)	5.00mm ±0.40mm	
Thickness(T)	2.50mm ±0.30mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)		
Recommended Land Pattern (PA)	4.10mm to 4.80mm	
Recommended Land Pattern (PB)	1.20mm to 1.40mm	_
Recommended Land Pattern (PC)	4.00mm to 5.00mm	

Electrical Characteristics		
Capacitance	6.8µF ±10%	
Rated Voltage	50VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	3%	
Insulation Resistance (Min.)	73ΜΩ	

<b>O</b> ther		
Soldering Method	Reflow	
AEC-Q200	Yes	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	500pcs	

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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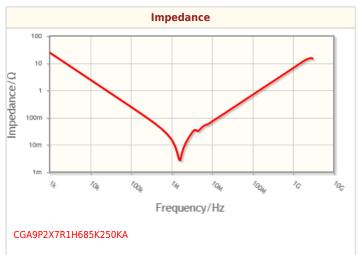


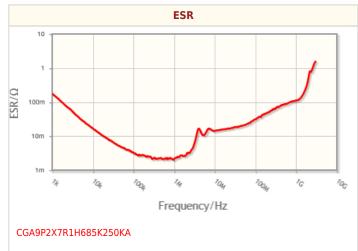


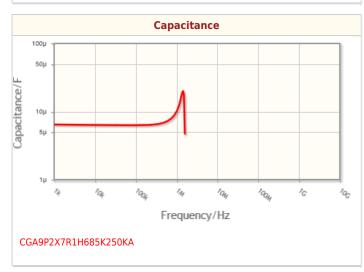




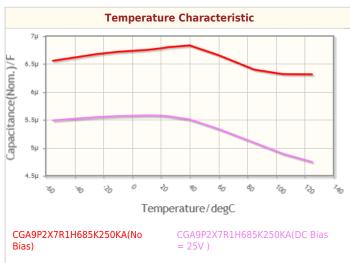
# Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

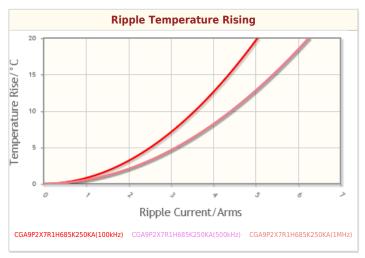












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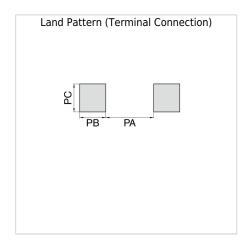








# **Associated Images**



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